

Binding treatment of copper sheet with improved binding strength and bottom cutting resistant

Publication number: CN1301130

Publication date: 2001-06-27

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Classification:

- international: **H05K3/38; H05K3/38; (IPC1-7): H05K3/38**


- european: **H05K3/38C4**


Application number: CN20000128414 20000929


Priority number(s): US19990408170 19990929

Also published as:

 EP1089603 (A2)

 US6342308 (B1)

 JP2001177205 (A)

 EP1089603 (A3)

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Abstract not available for CN1301130

Abstract of corresponding document: **EP1089603**

A treated electrodeposited copper foil having a bond-enhancing copper layer, preferably a plurality of layers, electrodeposited on a bonding side of a base copper foil, a layer of co-deposited copper and arsenic electrodeposited on the bond-enhancing layer, and a zinc or zinc alloy layer electrodeposited on the copper/arsenic layer. A process for making such foil, and a copper-clad laminate wherein such foil is bonded to a polymeric substrate.

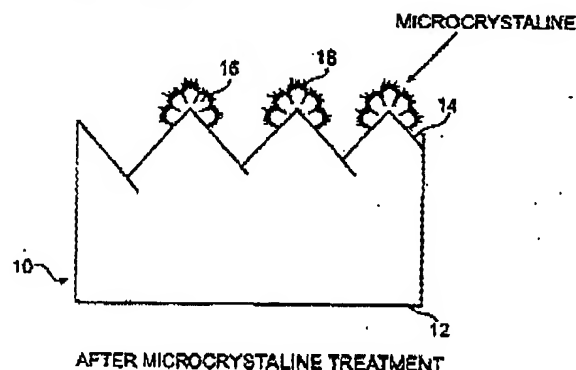


FIG. 2

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Cited reference documents 2

[19] 中华人民共和国国家知识产权局

[51] Int. Cl⁷

H05K 3/38

[12] 发明专利申请公开说明书

[21] 申请号 00128414.2

[43] 公开日 2001 年 6 月 27 日

[11] 公开号 CN 1301130A

[22] 申请日 2000.9.29 [21] 申请号 00128414.2

[30] 优先权

[32] 1999.9.29 [33] US [31] 09/408,170

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权利要求书 2 页 说明书 8 页 附图页数 3 页

[54] 发明名称 具有改良的粘结强度和耐底切性的铜箔
的粘结处理

[57] 摘要

本发明涉及一种处理的电沉积铜箔,其具有粘合—增强铜层,优选多层,其电沉积在基铜箔的粘合面上;还具有电沉积在粘合—增强层上的铜和砷共沉积层,和电沉积在铜/砷层上的锌或锌合金层。本发明还涉及一种制造这种箔和数铜箔叠片的方法,其中这种箔被粘接到聚合物衬底上。

ISSN 1008-4274

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